

ABSTRACT

~~Provided are a~~ A process for producing an electronic component ~~which is superior in heat dissipation property, helps to achieve low resistivity, and makes it possible to prevent detachment of the conductor part from the base material, and an electronic component produced by such a process.~~ The electronic component includes~~[[:]~~ a base material equipped with a core material and having a conductor layer on at least one surface thereof; a via hole formed through laser irradiation from the other surface side of the base material; a first plating layer formed by using the conductor layer as an electrode so as to cover the core material, which is exposed on an inner wall surface of the via hole; an electroless plating layer which is formed on the upper side of the first plating layer and which is in close contact with the inner wall surface of the via hole; and a second plating layer formed by using the conductor layer as an electrode so as to cover the electroless plating layer. A conductor part is formed in the via hole ~~by the first plating layer, the electroless plating layer, and the second plating layer.~~